

## **General Description**

The AAT8307 is a low threshold P Channel MOS-FET designed for the battery, cell phone, and PDA markets. Using AnalogicTech™'s proprietary ultrahigh density Trench technology, and space saving small outline J-lead package, performance superior to that normally found in a larger footprint has been squeezed into the area of a TSOP6 package.

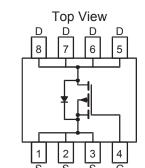
### **Features**

- $V_{DS(MAX)} = -20V$
- $I_{D(MAX)}^{(MAX)} = -6.0A @ 25^{\circ}C$
- Low  $R_{DS(ON)}$ :

  35 mΩ @  $V_{GS}$  = -4.5V

  60 mΩ @  $V_{GS}$  = -2.5V

### **TSOPJW-8 Package**



### **Applications**

- **Battery Packs**
- Cellular & Cordless Telephones
- Battery-powered portable equipment
- **Load Switches**

### **Absolute Maximum Ratings** (T<sub>A</sub>=25°C unless otherwise noted)

Symbol	Description		Value	Units	
V <sub>DS</sub>	Drain-Source Voltage		-20	V	
$V_{GS}$	Gate-Source Voltage		±12		
I <sub>D</sub>	Continuous Drain Current @ T <sub>J</sub> =150°C ¹	T <sub>A</sub> = 25°C	±6.0	Α	
		T <sub>A</sub> = 70°C	±4.8		
I <sub>DM</sub>	Pulsed Drain Current <sup>2</sup>		±32		
I <sub>S</sub>	Continuous Source Current (Source-Drain Diode) 1	ntinuous Source Current (Source-Drain Diode) 1			
P <sub>D</sub>	Maximum Power Dissipation <sup>1</sup>	$T_A = 25^{\circ}C$	2.1	W	
		T <sub>A</sub> = 70°C	1.3	V V	
T <sub>J</sub> , T <sub>STG</sub>	Operating Junction and Storage Temperature Range		-55 to 150	°C	

### **Thermal Characteristics**

Symbol	Description	Тур	Max	Units
$R_{\theta JA}$	Junction-to-Ambient steady state 1	90	110	°C/W
R <sub>0JA2</sub>	Junction-to-Ambient t<5 seconds 1	48	59	°C/W
$R_{\theta JF}$	Junction-to-Foot <sup>1</sup>	31	37	°C/W



### **Electrical Characteristics** (T<sub>J</sub>=25°C unless otherwise noted)

Symbol	Description	Conditions	Min	Тур	Max	Units	
DC Chara	DC Characteristics						
BV <sub>DSS</sub>	Drain-Source Breakdown Voltage	V <sub>GS</sub> =0V, I <sub>D</sub> =-250μA	-20			V	
R <sub>DS(ON)</sub>	Drain-Source ON-Resistance <sup>2</sup>	$V_{GS}$ =-4.5V, $I_{D}$ =-6.0A		27	35	mΩ	
		V <sub>GS</sub> =-2.5V, I <sub>D</sub> =-4.6A		46	60		
$I_{D(ON)}$	On-State Drain Current <sup>2</sup>	V <sub>GS</sub> =-4.5V, V <sub>DS</sub> =-5V (Pulsed)	-32			Α	
V <sub>GS(th)</sub>	Gate Threshold Voltage	$V_{GS}=V_{DS}$ , $I_{D}=-250\mu A$	-0.6			V	
I <sub>GSS</sub>	Gate-Body Leakage Current	V <sub>GS</sub> =±12V, V <sub>DS</sub> =0V			±100	nA	
I <sub>DSS</sub>	Drain Source Leakage Current	V <sub>GS</sub> =0V, V <sub>DS</sub> =-20V			-1		
		V <sub>GS</sub> =0V, V <sub>DS</sub> =-16V, T <sub>J</sub> =70°C <sup>3</sup>			-5	μΑ	
g <sub>fs</sub>	Forward Transconductance <sup>2</sup>	$V_{DS}$ =-5V, $I_D$ =-6.0A		12		S	
Dynamic	Dynamic Characteristics <sup>3</sup>					•	
$Q_G$	Total Gate Charge	$V_{DS}$ =-15V, $R_{D}$ =2.5 $\Omega$ , $V_{GS}$ =-4.5V		14			
$Q_{GS}$	Gate-Source Charge	$V_{DS}$ =-15V, $R_{D}$ =2.5 $\Omega$ , $V_{GS}$ =-4.5V		2.3		nC	
$Q_{GD}$	Gate-Drain Charge	$V_{DS}$ =-15V, $R_{D}$ =2.5 $\Omega$ , $V_{GS}$ =-4.5V		5.5			
t <sub>D(ON)</sub>	Turn-ON Delay	$V_{DD}$ =-15V, $V_{GS}$ =-4.5V, $R_{D}$ =2.5 $\Omega$ , $R_{G}$ =6 $\Omega$		10			
t <sub>R</sub>	Turn-ON Rise Time	$V_{DD}$ =-15V, $V_{GS}$ =-4.5V, $R_{D}$ =2.5 $\Omega$ , $R_{G}$ =6 $\Omega$		37		ns	
t <sub>D(OFF)</sub>	Turn-OFF Delay	$V_{DD}$ =-15V, $V_{GS}$ =-4.5V, $R_{D}$ =2.5 $\Omega$ , $R_{G}$ =6 $\Omega$		36		115	
t <sub>F</sub>	Turn-OFF Fall Time	$V_{DD}$ =-15V, $V_{GS}$ =-4.5V, $R_{D}$ =2.5 $\Omega$ , $R_{G}$ =6 $\Omega$		52			
Source-Drain Diode Characteristics							
$V_{SD}$	Source-Drain Forward Voltage <sup>2</sup>	V <sub>GS</sub> =0, I <sub>S</sub> =-6.0A			-1.2	V	
I <sub>S</sub>	Continuous Diode Current <sup>1</sup>				-1.9	Α	

Note 1: Based on thermal dissipation from junction to ambient while mounted on a 1" x 1" PCB with optimized layout. A 5 second pulse on a 1" x 1" PCB approximates testing a device mounted on a large multi-layer PCB as in most applications.  $R_{\theta JF} + R_{\theta FA} = R_{\theta JA}$  where the foot thermal reference is defined as the normal solder mounting surface of the device's leads.  $R_{\theta JF}$  is guaranteed by design, however  $R_{\theta CA}$  is determined by the PCB design. Actual maximum continuous current is limited by the application's design.

Note 2: Pulse test: Pulse Width = 300 μs

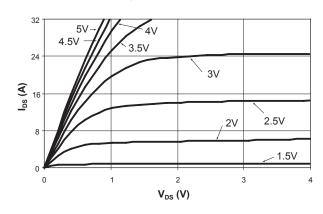
Note 3: Guaranteed by design. Not subject to production testing.



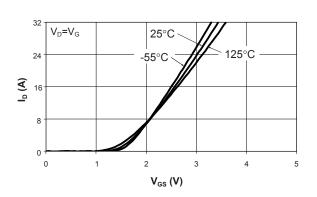
# **Typical Characteristics**

 $\overline{(T_1 = 25^{\circ}\text{C unless otherwise noted)}}$ 

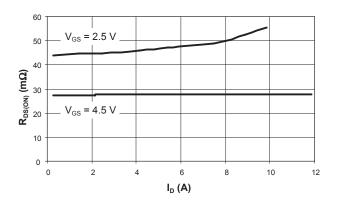
#### **Output Characteristics**



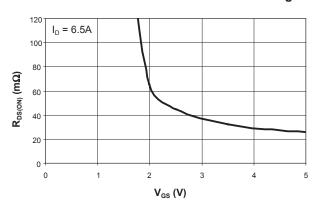
#### **Transfer Characteristics**



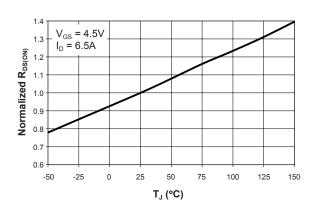
On-Resistance vs. Drain Current



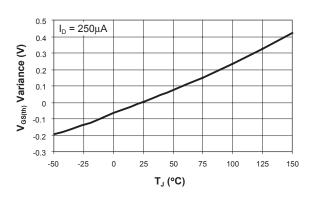
On-Resistance vs. Gate to Source Voltage



On-Resistance vs. Junction Temperature



Threshold Voltage

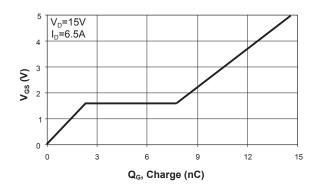




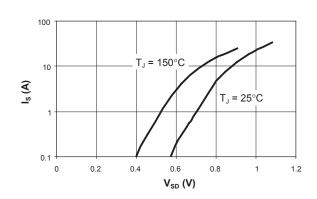
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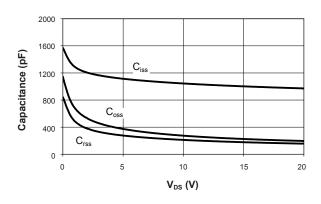
### **Gate Charge**



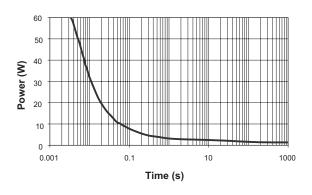
#### Source-Drain Diode Forward Voltage



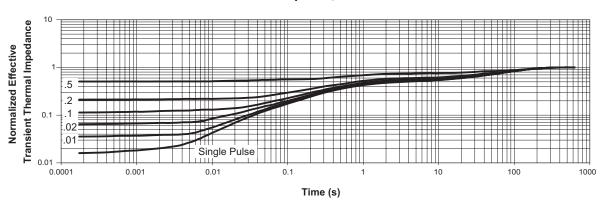
Capacitance



Single Pulse Power, Junction to Ambient



**Transient Thermal Response, Junction to Ambient** 



4 8307.2003.06.0.62



# **Ordering Information**

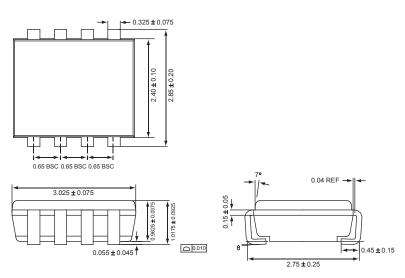
Package	Marking <sup>1</sup>	Part Number (Tape and Reel)
TSOPJW-8	ICXYY	AAT8307ITS-T1

Note: Sample stock is generally held on all part numbers listed in BOLD.

Note 1: XYY = assembly and date code.

# **Package Information**

#### TSOPJW-8



All dimensions in millimeters.



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